

PROBE SYSTEM FOR QFP INTEGRATED CIRCUIT DEVICE TEST

TOOLING

ABSTRACT

An automated high speed test solution for Quad Flat Pack device packages that enables connectivity between test equipment and the integrated circuit under test is described. A test probe geometry that provides highly repeatable and reliable connections suitable for use with consumer grade QFP devices coupled with ease of maintenance is provided. In some embodiments, the probe tip ends are chisel-shaped. The probes can be slightly slanted with respect to a vertical axis of the probe retaining block.

Figure 1